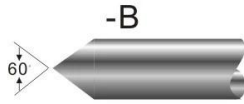


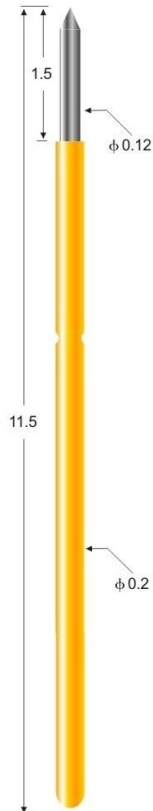
Product Specification

Brand	SFENG
Item number	SF-P080
Plunger	Brass
Barrel	Brass
Spring	SUS or Music wire
Spring Force	15g
Full Travel	1.5(0.0590")
Current Ration	0.3A
Current Resistance	260mW
Pitch	0.45(0.0177")
Mounting hole size	0.35(0.0138")
MOQ	100 pcs
Lead time	7 working days after receiving the payment

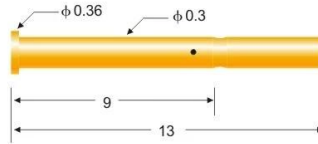
Product Picture



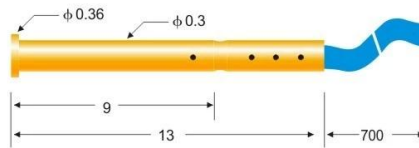
-J



SF-P080-B



SF-R080-VR



SF-R080-VRW

Probe specifications SF-P080 (技术规格)

- Recommended minimum center(最小间距): 0.45mm(.0177 ")
- Mounting hole size(钻孔尺寸): 0.35mm(.0138 ")
- Full travel(行程): 1.5(.0590 ")
- Spring force(弹簧压力): 15g(克)
- Materials and finishes(材料及涂饰):
Plunger: SK4, Rh plated
Barrel: Phosphor bronze, Gold plated
Spring: Music wire, Gold plated
- Current ration(额定电流): 0.3A(安培)
- Contact resistance(接触电阻): 260mΩ(毫欧姆)

Receptacle specifications

Materials and finishes: Phosphor bronze, Gold plated

1. We can reply your inquiry within 24 working hours.
2. Customized design is available and OEM are welcomed.
3. We can deliver the probe pins to our clients all over the world with speed and precision.
4. We can provide the lowest price with high quality product to our client .

Main Products

Spring loaded pin (single) for PCB, ICT, FCT testing etc;

Pogo pin (connector) to establish connection between two printed circuit boards for charging, locating, Battery, Semiconductor & Interconnect applications;

Double ended probe for BGA and Semiconductor testing;

Universal pin without spring, coating pin, LM pin with QZ and VZ series;

High current probe, Switch probe, Capacitance needle;

Terminal & receptacle /socket;

Other related electronic components, 30# OK wire, Jig locks, POM, Iron hinge etc

Production Flow



1. raw material warehouse



2. Lathe workshop



3. Assemble workshop



4. Quality inspection



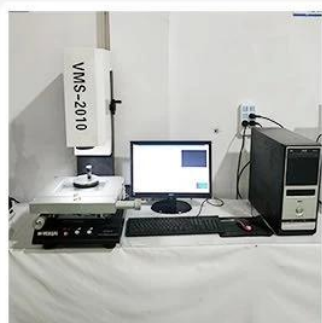
5. Finished products



6. Packing

Measuring Equipment

Measuring Equipment ➤



Measuring Equipment:

1. Agilent current testing;
2. Quadratic element measurement
3. Load Curve Meter
4. Bond Test
5. Life Fatigue Test